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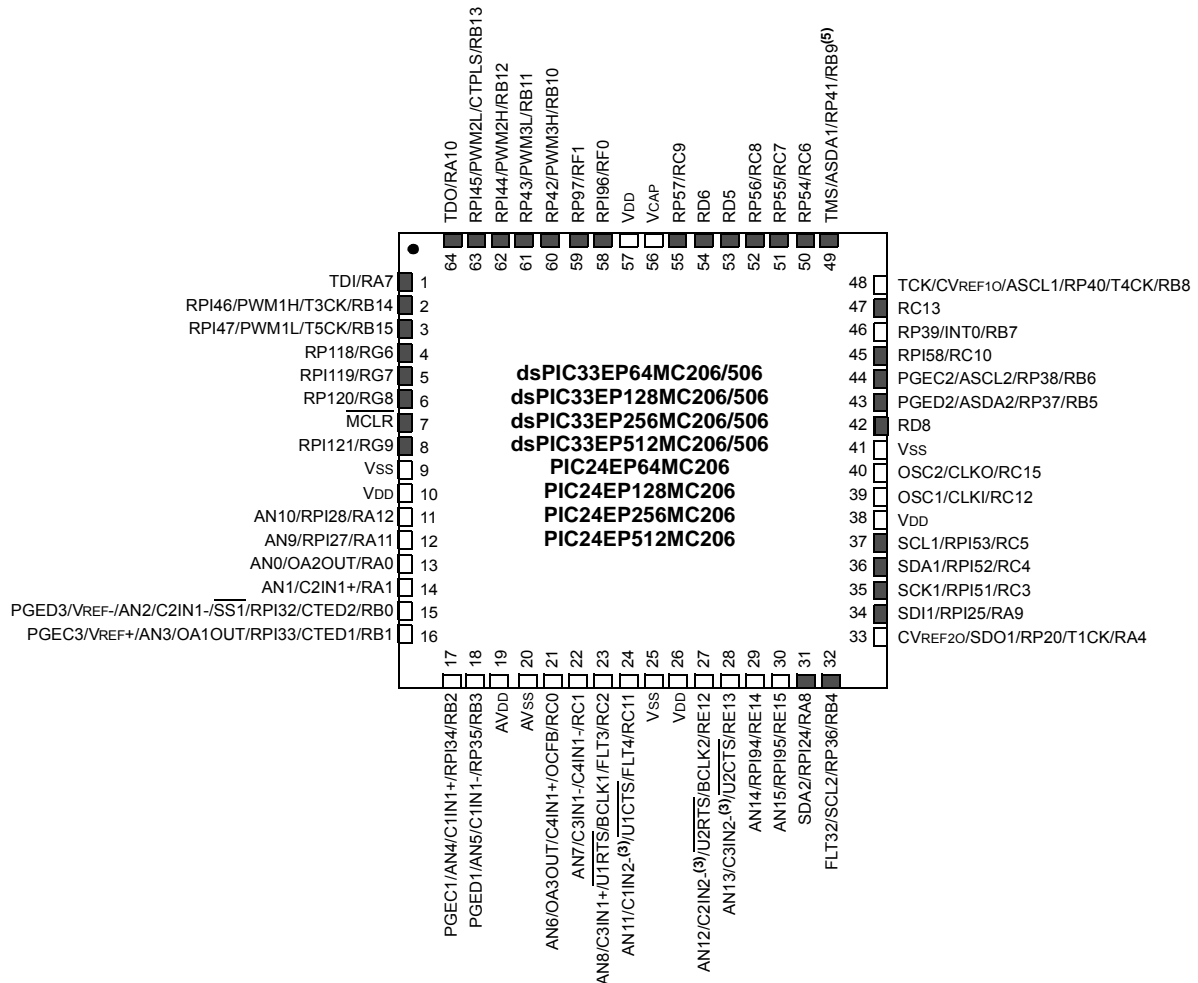
Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512mc206-i-mr

Pin Diagrams (Continued)

64-Pin QFN^(1,2,3,4)

■ = Pins are up to 5V tolerant



- Note**
- 1: The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
 - 2: Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
 - 3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.
 - 4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
 - 5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

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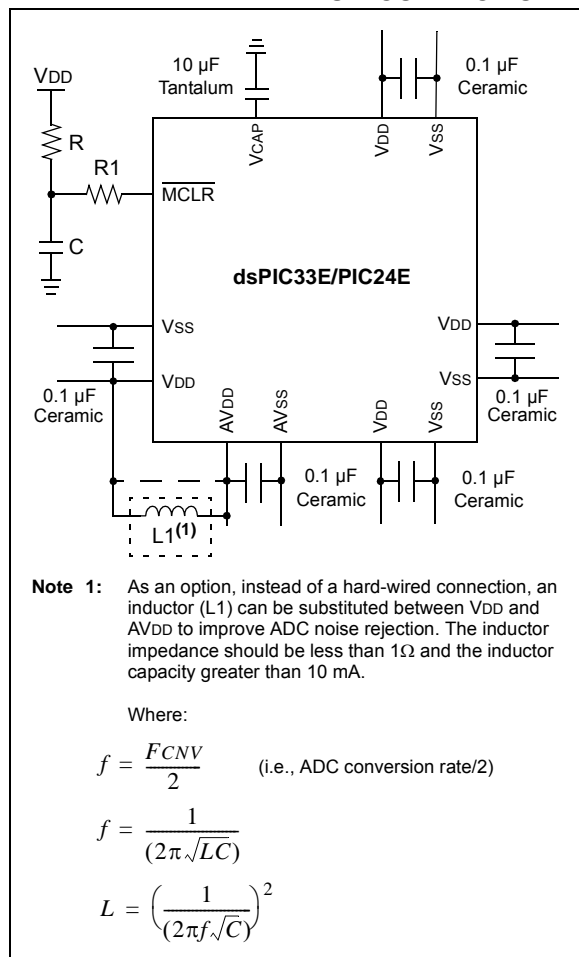
- Microchip's Worldwide Web site; **<http://www.microchip.com>**
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FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohm) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 30.0 “Electrical Characteristics”** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 27.3 “On-Chip Voltage Regulator”** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

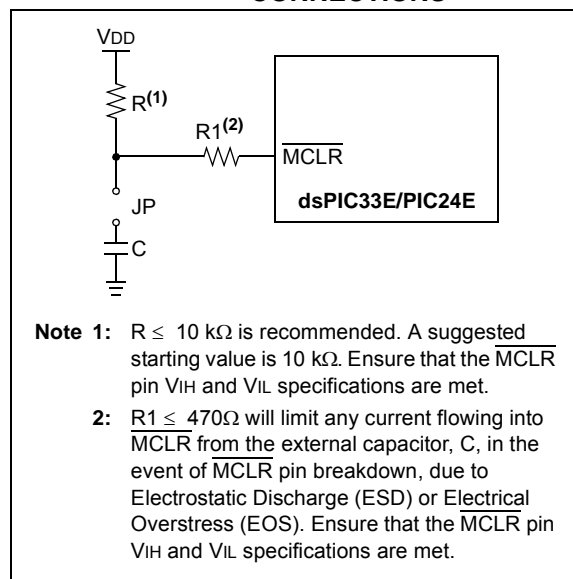
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to $3 \text{ MHz} < F_{IN} < 5.5 \text{ MHz}$ to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

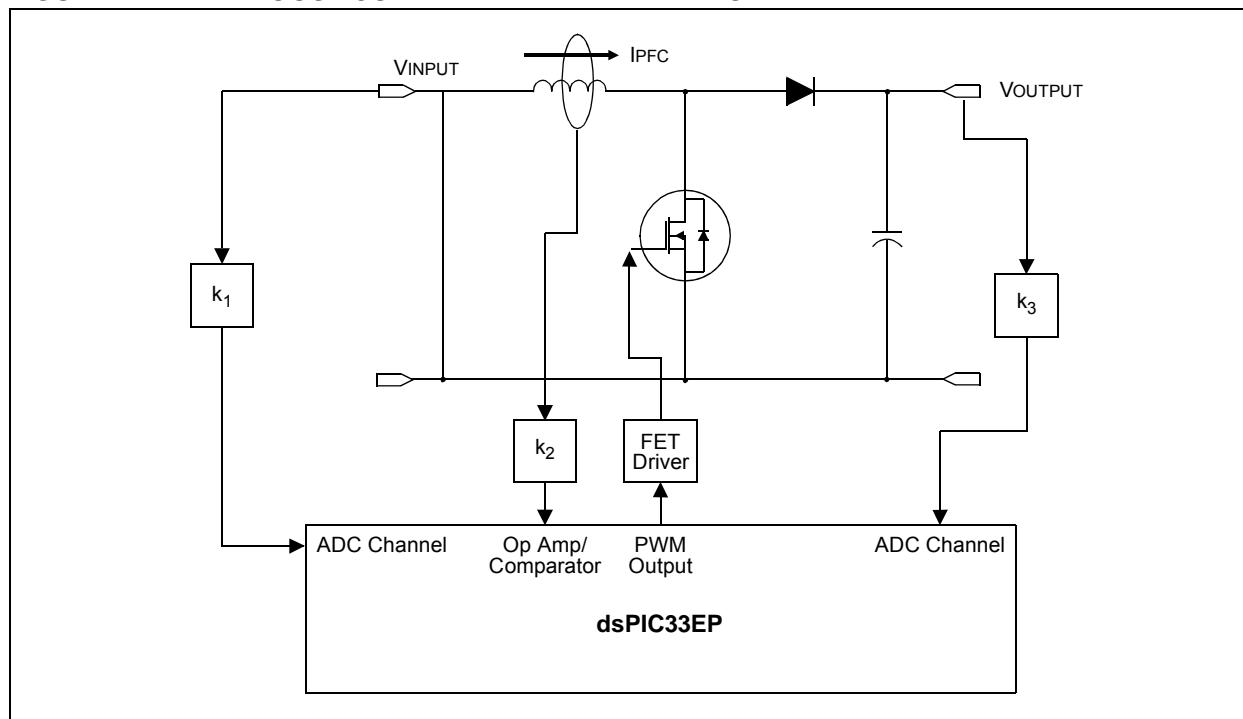
Alternatively, connect a 1k to 10k resistor between Vss and unused pins, and drive the output to logic low.

2.9 Application Examples

- Induction heating
- Uninterruptable Power Supplies (UPS)
- DC/AC inverters
- Compressor motor control
- Washing machine 3-phase motor control
- BLDC motor control
- Automotive HVAC, cooling fans, fuel pumps
- Stepper motor control
- Audio and fluid sensor monitoring
- Camera lens focus and stability control
- Speech (playback, hands-free kits, answering machines, VoIP)
- Consumer audio
- Industrial and building control (security systems and access control)
- Barcode reading
- Networking: LAN switches, gateways
- Data storage device management
- Smart cards and smart card readers

Examples of typical application connections are shown in Figure 2-4 through Figure 2-8.

FIGURE 2-4: BOOST CONVERTER IMPLEMENTATION



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**CPU**” (DS70359) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (MOV.D) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the DO and REPEAT instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

3.2 Instruction Set

The instruction set for dsPIC33EPXXXGP50X and dsPIC33EPXXXMC20X/50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. The instruction set for PIC24EPXXXGP/MC20X devices has the MCU class of instructions only and does not support DSP instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as 64 Kbytes (32K words).

The Data Space includes two ranges of memory, referred to as X and Y data memory. Each memory range is accessible through its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Spaces have memory locations that are device-specific, and are described further in the data memory maps in **Section 4.2 “Data Address Space”**.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 32-Kbyte aligned program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. Refer to the “**Data Memory**” (DS70595) and “**Program Memory**” (DS70613) sections in the “*dsPIC33/PIC24 Family Reference Manual*” for more details on EDS, PSV and table accesses.

On the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms. PIC24EPXXXGP/MC20X devices do not support Modulo and Bit-Reversed Addressing.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

3.8 Arithmetic Logic Unit (ALU)

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X ALU is 16 bits wide, and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. Depending on the operation, the ALU can affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as Borrow and Digit Borrow bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the “16-bit MCU and DSC Programmer's Reference Manual” (DS70157) for information on the SR bits affected by each instruction.

The core CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit divisor division.

3.8.1 MULTIPLIER

Using the high-speed 17-bit x 17-bit multiplier, the ALU supports unsigned, signed, or mixed-sign operation in several MCU multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit signed x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.8.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

- 32-bit signed/16-bit signed divide
- 32-bit unsigned/16-bit unsigned divide
- 16-bit signed/16-bit signed divide
- 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. The 16-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.9 DSP Engine (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X Devices Only)

The DSP engine consists of a high-speed 17-bit x 17-bit multiplier, a 40-bit barrel shifter and a 40-bit adder/subtractor (with two target accumulators, round and saturation logic).

The DSP engine can also perform inherent accumulator-to-accumulator operations that require no additional data. These instructions are `ADD`, `SUB` and `NEG`.

The DSP engine has options selected through bits in the CPU Core Control register (CORCON), as listed below:

- Fractional or integer DSP multiply (IF)
- Signed, unsigned or mixed-sign DSP multiply (US)
- Conventional or convergent rounding (RND)
- Automatic saturation on/off for ACCA (SATA)
- Automatic saturation on/off for ACCB (SATB)
- Automatic saturation on/off for writes to data memory (SATDW)
- Accumulator Saturation mode selection (ACCSAT)

TABLE 3-2: DSP INSTRUCTIONS SUMMARY

Instruction	Algebraic Operation	ACC Write Back
CLR	$A = 0$	Yes
ED	$A = (x - y)^2$	No
EDAC	$A = A + (x - y)^2$	No
MAC	$A = A + (x \cdot y)$	Yes
MAC	$A = A + x^2$	No
MOVSAC	No change in A	Yes
MPY	$A = x \cdot y$	No
MPY	$A = x^2$	No
MPY.N	$A = -x \cdot y$	No
MSC	$A = A - x \cdot y$	Yes

FIGURE 4-14: DATA MEMORY MAP FOR PIC24EP128GP/MC20X/50X DEVICES

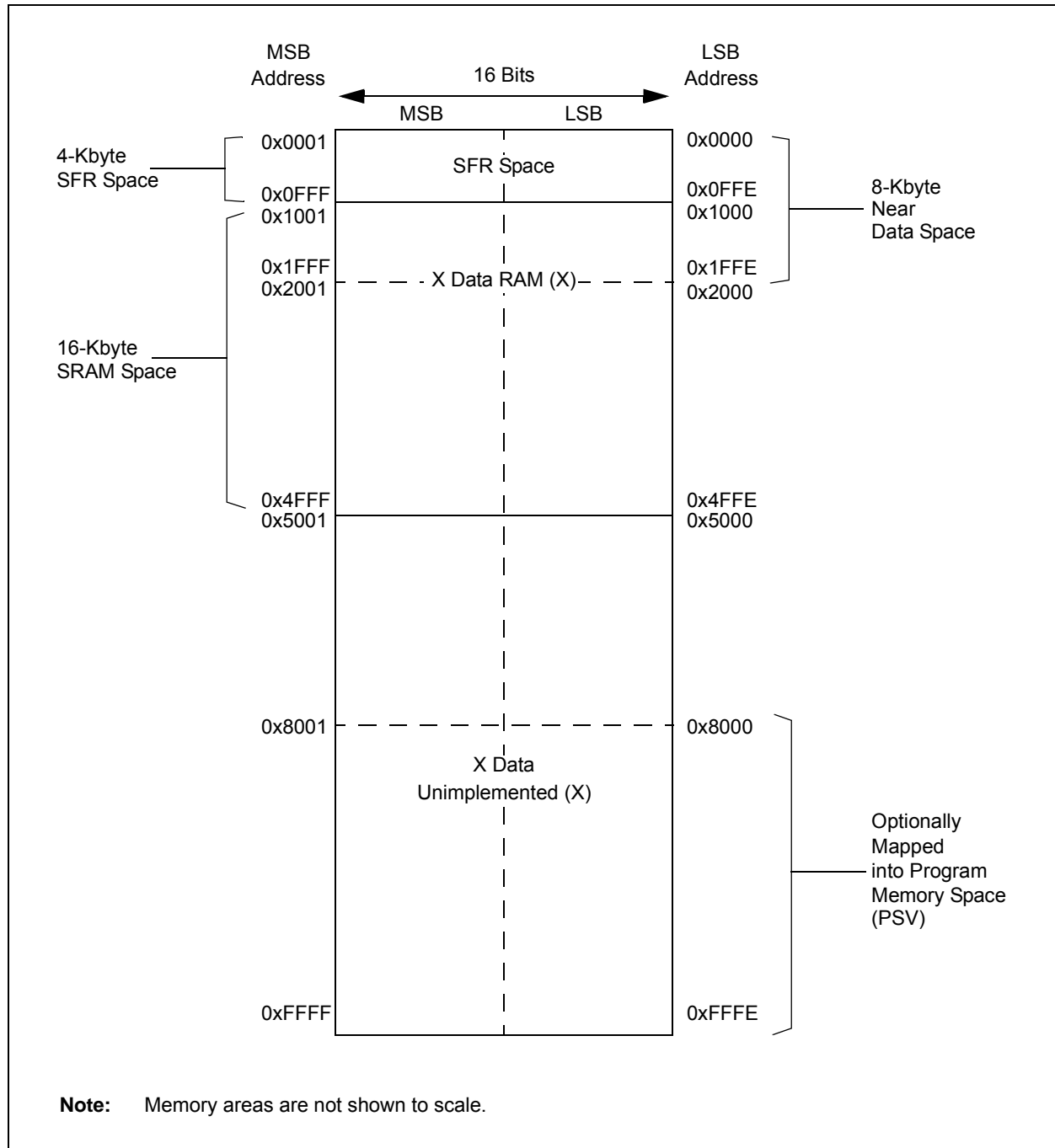


TABLE 4-10: OUTPUT COMPARE 1 THROUGH OUTPUT COMPARE 4 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1CON1	0900	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC1CON2	0902	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC1RS	0904	Output Compare 1 Secondary Register																xxxx
OC1R	0906	Output Compare 1 Register																xxxx
OC1TMR	0908	Timer Value 1 Register																xxxx
OC2CON1	090A	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC2CON2	090C	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC2RS	090E	Output Compare 2 Secondary Register																xxxx
OC2R	0910	Output Compare 2 Register																xxxx
OC2TMR	0912	Timer Value 2 Register																xxxx
OC3CON1	0914	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC3CON2	0916	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC3RS	0918	Output Compare 3 Secondary Register																xxxx
OC3R	091A	Output Compare 3 Register																xxxx
OC3TMR	091C	Timer Value 3 Register																xxxx
OC4CON1	091E	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC4CON2	0920	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC4RS	0922	Output Compare 4 Secondary Register																xxxx
OC4R	0924	Output Compare 4 Register																xxxx
OC4TMR	0926	Timer Value 4 Register																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-53: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	—	—	TRISA10	TRISA9	TRISA8	TRISA7	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	079F
PORTA	0E02	—	—	—	—	—	RA10	RA9	RA8	RA7	—	—	RA4	RA3	RA2	RA1	RA0	0000
LATA	0E04	—	—	—	—	—	LATA10	LATA9	LATA8	LATA7	—	—	LATA4	LATA3	LATA2	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	—	—	ODCA10	ODCA9	ODCA8	ODCA7	—	—	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	—	—	CNIEA10	CNIEA9	CNIEA8	CNIEA7	—	—	CNIEA4	CNIEA3	CNIEA2	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	—	—	CNPUA10	CNPUA9	CNPUA8	CNPUA7	—	—	CNPUA4	CNPUA3	CNPUA2	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	—	—	CNPDA10	CNPDA9	CNPDA8	CNPDA7	—	—	CNPDA4	CNPDA3	CNPDA2	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	—	—	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	0013

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-54: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-55: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	—	—	—	—	—	—	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF
PORTC	0E22	—	—	—	—	—	—	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATC	0E24	—	—	—	—	—	—	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	0E26	—	—	—	—	—	—	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000
CNENC	0E28	—	—	—	—	—	—	CNIEC9	CNIEC8	CNIEC7	CNIEC6	CNIEC5	CNIEC4	CNIEC3	CNIEC2	CNIEC1	CNIEC0	0000
CNPUC	0E2A	—	—	—	—	—	—	CNPUC9	CNPUC8	CNPUC7	CNPUC6	CNPUC5	CNPUC4	CNPUC3	CNPUC2	CNPUC1	CNPUC0	0000
CNPDC	0E2C	—	—	—	—	—	—	CNPDC9	CNPDC8	CNPDC7	CNPDC6	CNPDC5	CNPDC4	CNPDC3	CNPDC2	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	—	—	—	—	—	—	—	—	—	ANSC2	ANSC1	ANSC0	0007

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

11.4 Peripheral Pin Select (PPS)

A major challenge in general purpose devices is providing the largest possible set of peripheral features while minimizing the conflict of features on I/O pins. The challenge is even greater on low pin count devices. In an application where more than one peripheral needs to be assigned to a single pin, inconvenient work-arounds in application code, or a complete redesign, may be the only option.

Peripheral Pin Select configuration provides an alternative to these choices by enabling peripheral set selection and their placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, users can better tailor the device to their entire application, rather than trimming the application to fit the device.

The Peripheral Pin Select configuration feature operates over a fixed subset of digital I/O pins. Users may independently map the input and/or output of most digital peripherals to any one of these I/O pins. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping once it has been established.

11.4.1 AVAILABLE PINS

The number of available pins is dependent on the particular device and its pin count. Pins that support the Peripheral Pin Select feature include the label, “RPn” or “RPI n”, in their full pin designation, where “n” is the remappable pin number. “RP” is used to designate pins that support both remappable input and output functions, while “RPI” indicates pins that support remappable input functions only.

11.4.2 AVAILABLE PERIPHERALS

The peripherals managed by the Peripheral Pin Select are all digital-only peripherals. These include general serial communications (UART and SPI), general purpose timer clock inputs, timer-related peripherals (input capture and output compare) and interrupt-on-change inputs.

In comparison, some digital-only peripheral modules are never included in the Peripheral Pin Select feature. This is because the peripheral's function requires special I/O circuitry on a specific port and cannot be easily connected to multiple pins. These modules include I²C™ and the PWM. A similar requirement excludes all modules with analog inputs, such as the ADC Converter.

A key difference between remappable and non-remappable peripherals is that remappable peripherals are not associated with a default I/O pin. The peripheral must always be assigned to a specific I/O pin before it can be used. In contrast, non-remappable peripherals are always available on a default pin, assuming that the peripheral is active and not conflicting with another peripheral.

When a remappable peripheral is active on a given I/O pin, it takes priority over all other digital I/O and digital communication peripherals associated with the pin. Priority is given regardless of the type of peripheral that is mapped. Remappable peripherals never take priority over any analog functions associated with the pin.

11.4.3 CONTROLLING PERIPHERAL PIN SELECT

Peripheral Pin Select features are controlled through two sets of SFRs: one to map peripheral inputs and one to map outputs. Because they are separately controlled, a particular peripheral's input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

The association of a peripheral to a peripheral-selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

REGISTER 16-17: LEBDLYx: PWMx LEADING-EDGE BLANKING DELAY REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

REGISTER 17-3: QE1STAT: QE1 STATUS REGISTER (CONTINUED)

bit 2	HOMIEN: Home Input Event Interrupt Enable bit 1 = Interrupt is enabled 0 = Interrupt is disabled
bit 1	IDXIRQ: Status Flag for Index Event Status bit 1 = Index event has occurred 0 = No Index event has occurred
bit 0	IDXIEN: Index Input Event Interrupt Enable bit 1 = Interrupt is enabled 0 = Interrupt is disabled

Note 1: This status bit is only applicable to PIMOD<2:0> modes, '011' and '100'.

BUFFER 21-5: ECAN™ MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3							
bit 15							
bit 8							

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2							
bit 7							
bit 0							

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-8 **Byte 3<15:8>**: ECAN Message Byte 3 bits

bit 7-0 **Byte 2<7:0>**: ECAN Message Byte 2 bits

BUFFER 21-6: ECAN™ MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5							
bit 15							
bit 8							

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4							
bit 7							
bit 0							

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-8 **Byte 5<15:8>**: ECAN Message Byte 5 bits

bit 7-0 **Byte 4<7:0>**: ECAN Message Byte 4 bits

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 0

CH123SA: Channel 1, 2, 3 Positive Input Select for Sample MUXA bitIn 12-bit mode (AD21B = 1), CH123SA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1 ⁽²⁾	OA1/AN3	OA2/AN0	OA3/AN6
0 ^(1,2)	OA2/AN0	AN1	AN2

- Note 1:** AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.
- 2:** The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

FIGURE 25-2: COMPARATOR MODULE BLOCK DIAGRAM (MODULE 4)

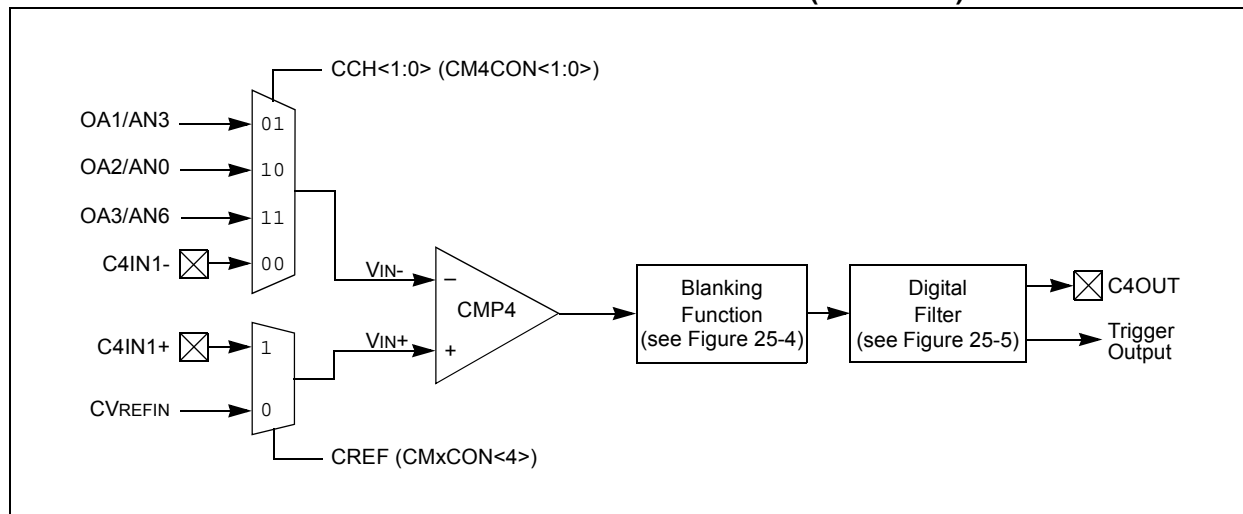


FIGURE 25-3: OP AMP/COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM

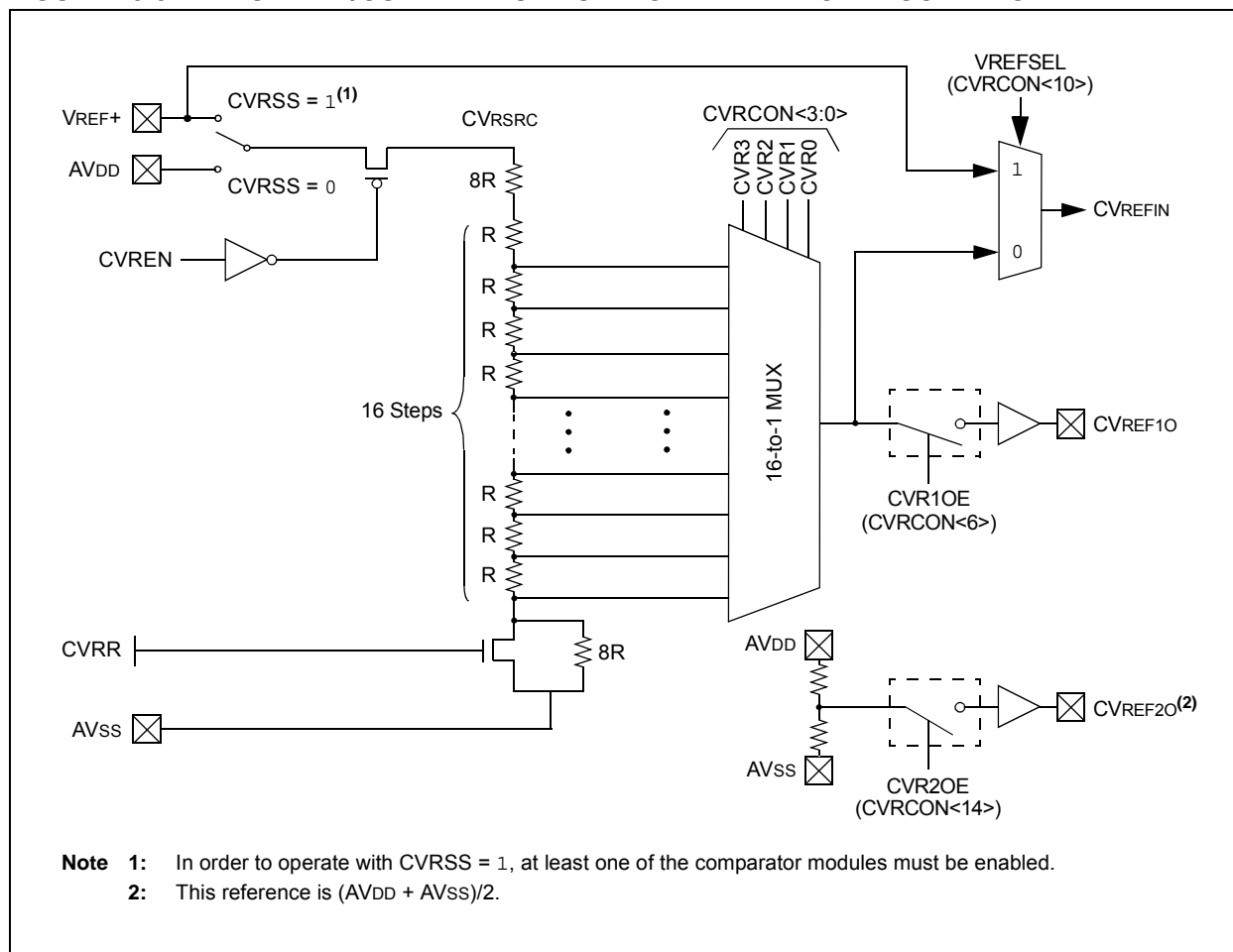


TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
53	NEG	NEG $Acc^{(1)}$	Negate Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		NEG f	$f = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG $f, WREG$	$WREG = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG Ws, Wd	$Wd = \bar{Ws} + 1$	1	1	C,DC,N,OV,Z
54	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
55	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to $W(nd):W(nd + 1)$	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
56	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push $W(ns):W(ns + 1)$ to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
57	PWRSV	PWRSV $\#lit1$	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL $Expr$	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT $\#lit15$	Repeat Next Instruction $lit15 + 1$ times	1	1	None
		REPEAT Wn	Repeat Next Instruction $(Wn) + 1$ times	1	1	None
60	RESET	RESET	Software device Reset	1	1	None
61	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW $\#lit10, Wn$	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN	Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC f	$f = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC $f, WREG$	$WREG = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC Ws, Wd	$Wd = \text{Rotate Left through Carry } Ws$	1	1	C,N,Z
65	RLNC	RLNC f	$f = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC $f, WREG$	$WREG = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC Ws, Wd	$Wd = \text{Rotate Left (No Carry) } Ws$	1	1	N,Z
66	RRC	RRC f	$f = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC $f, WREG$	$WREG = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC Ws, Wd	$Wd = \text{Rotate Right through Carry } Ws$	1	1	C,N,Z
67	RRNC	RRNC f	$f = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC $f, WREG$	$WREG = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC Ws, Wd	$Wd = \text{Rotate Right (No Carry) } Ws$	1	1	N,Z
68	SAC	SAC $Acc, \#Slit4, Wdo^{(1)}$	Store Accumulator	1	1	None
		SAC.R $Acc, \#Slit4, Wdo^{(1)}$	Store Rounded Accumulator	1	1	None
69	SE	SE Ws, Wnd	$Wnd = \text{sign-extended } Ws$	1	1	C,N,Z
70	SETM	SETM f	$f = 0xFFFF$	1	1	None
		SETM $WREG$	$WREG = 0xFFFF$	1	1	None
		SETM Ws	$Ws = 0xFFFF$	1	1	None
71	SFTAC	SFTAC $Acc, Wn^{(1)}$	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB,SA,SB,SAB
		SFTAC $Acc, \#Slit6^{(1)}$	Arithmetic Shift Accumulator by $Slit6$	1	1	OA,OB,OAB,SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})⁽¹⁾

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	Typ.	Max.	Units	Conditions	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base IPD current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

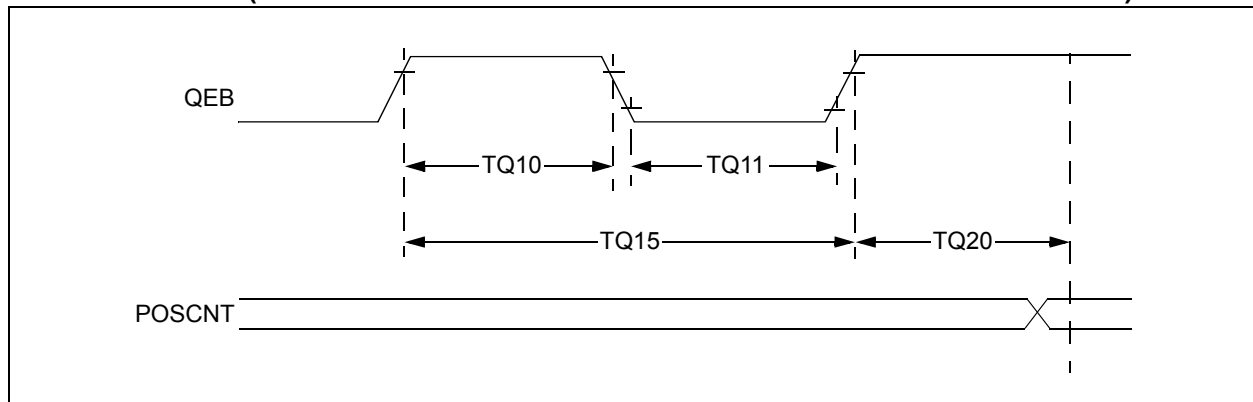
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	Typ.	Max.	Doze Ratio	Units	Conditions
Doze Current (IDOZE)⁽¹⁾					
DC73a ⁽²⁾	35	—	1:2	mA	-40°C 3.3V Fosc = 140 MHz
DC73g	20	30	1:128	mA	
DC70a ⁽²⁾	35	—	1:2	mA	+25°C 3.3V Fosc = 140 MHz
DC70g	20	30	1:128	mA	
DC71a ⁽²⁾	35	—	1:2	mA	+85°C 3.3V Fosc = 140 MHz
DC71g	20	30	1:128	mA	
DC72a ⁽²⁾	28	—	1:2	mA	+125°C 3.3V Fosc = 120 MHz
DC72g	15	30	1:128	mA	

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to Vss
- \overline{MCLR} = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

**FIGURE 30-11: TIMERQ (QEI MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS
(dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)**

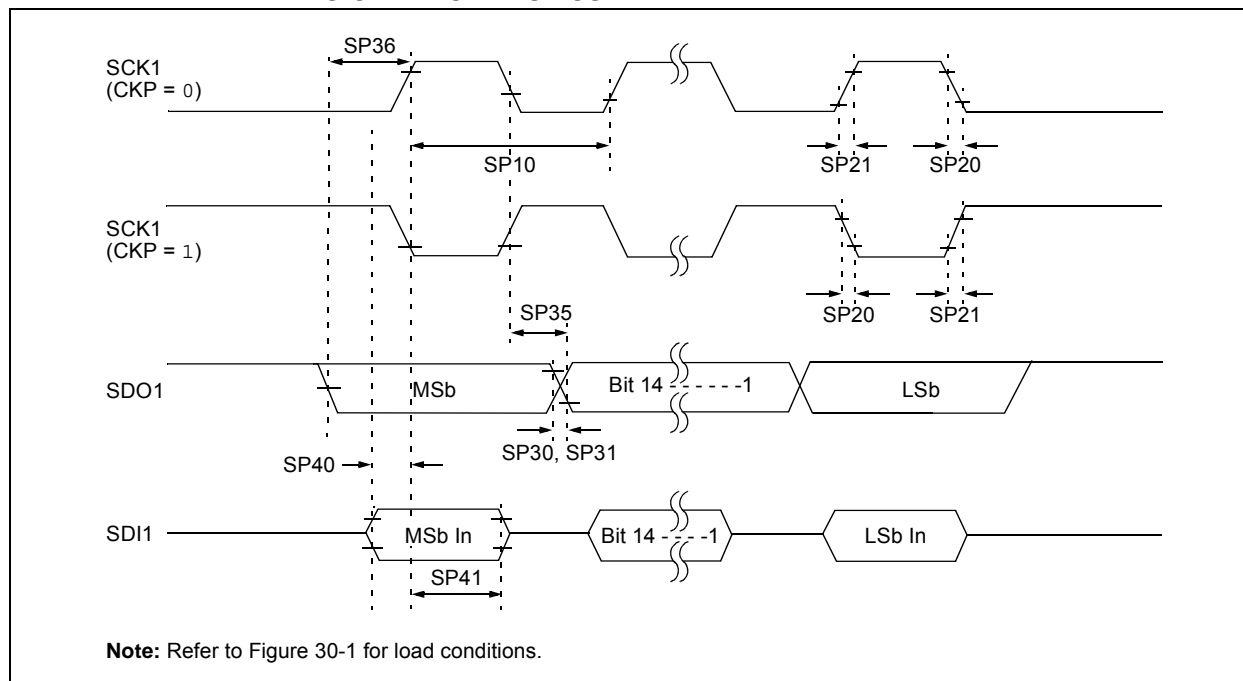


**TABLE 30-30: QEI MODULE EXTERNAL CLOCK TIMING REQUIREMENTS
(dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)**

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾		Min.	Typ.	Max.	Units	Conditions
TQ10	TtQH	TQCK High Time	Synchronous, with prescaler	Greater of $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	—	ns	Must also meet Parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with prescaler	Greater of $12.5 + 25$ or $(0.5 T_{CY}/N) + 25$	—	—	ns	Must also meet Parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with prescaler	Greater of $25 + 50$ or $(1 T_{CY}/N) + 50$	—	—	ns	
TQ20	TCKEXTMRL	Delay from External TQCK Clock Edge to Timer Increment		—	1	T_{CY}	—	

Note 1: These parameters are characterized but not tested in manufacturing.

**FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING CHARACTERISTICS**



**TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	(Note 3)
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2sch, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-56: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
CTMU Current Source							
CTMUI1	IOUT1	Base Range ⁽¹⁾	0.29	—	0.77	μA	CTMUICON<9:8> = 01
CTMUI2	IOUT2	10x Range ⁽¹⁾	3.85	—	7.7	μA	CTMUICON<9:8> = 10
CTMUI3	IOUT3	100x Range ⁽¹⁾	38.5	—	77	μA	CTMUICON<9:8> = 11
CTMUI4	IOUT4	1000x Range ⁽¹⁾	385	—	770	μA	CTMUICON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage ^(1,2)	—	0.598	—	V	TA = +25°C, CTMUICON<9:8> = 01
			—	0.658	—	V	TA = +25°C, CTMUICON<9:8> = 10
			—	0.721	—	V	TA = +25°C, CTMUICON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change ^(1,2,3)	—	-1.92	—	mV/°C	CTMUICON<9:8> = 01
			—	-1.74	—	mV/°C	CTMUICON<9:8> = 10
			—	-1.56	—	mV/°C	CTMUICON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUICON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing.

3: Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksp/s
- All PMDx bits are cleared (PMDx = 0)
- Executing a `while(1)` statement
- Device operating from the FRC with no PLL